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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
SHAO-YU TING, JACK LIANG, and KUO-JU LIU

Additional name of conveying party(ies) attached Yes No

01/07/02

Name and Address of Receiving Party(ies):

Name: WINBOND ELECTRONICS CORP.

Address: No. 4, Creation Rd., III, Science-Based Industrial Park, HSINCHU, TAIWAN

3. Nature of Conveyance: **Assignment**

Execution Date: **11/05/01**

Additional name(s) & address(es) attached Yes No

4. Application number(s) or patent number(s):

This document is being filed together with a new application on even date.

Title: **METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICES HAVING COPPER INTERCONNECT AND LOW-K DIELECTRIC LAYER**

Patent Application Ser. No(s). and Filing Date(s):

Patent No(s).:

5. Name and Address of Party To Whom Correspondence Concerning Document Should Be Mailed:

Name: **W. Wayne Liauh**
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6. Total Number of Applications and Patents Involved:

1

7. Total Fee (37 CFR 1.21(h)).....:

\$ 40.00

8. Deposit account number:

50-1260

8.

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

W. Wayne Liauh
Name of Person Signing

Signature

01/07/02
Date

Total number of pages comprising cover sheet: 1

01/23/2002 GT0N11 00000390 501260 10042995
01 FC:581 40.00 CH

ASSIGNMENT

WHEREAS, I (We), as named below and whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain and useful improvements in:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICES HAVING COPPER INTERCONNECT AND LOW-K DIELECTRIC LAYER

for which application for Letters Patent of the United States has been executed on even date herewith;

WHEREAS, **WINBOND ELECTRONICS CORP.**, whose post office address is: **No. 4, Creation Rd., III, Science-Based Industrial Park, HSINCHU, TAIWAN**, hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to said invention in the United States, and throughout the world;

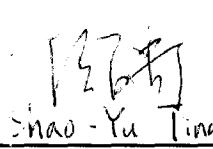
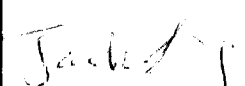
NOW, THEREFORE, for good and valuable consideration, the receipt of all of which is hereby acknowledged, ASSIGNOR hereby sells, assigns and transfers unto ASSIGNEE the full and exclusive right, title and interest in and to said invention in the United States, and throughout the world, including priority rights created by any treaty or international convention to which the United States of America is a party, said patent application, and in and to any patent or patents obtained on said invention in the United States and all foreign countries, as fully set forth and described in the specification executed by me (us) under even date herewith preparatory to obtaining Letters Patent of the United States therefor, including any continuations, divisions, renewals, reissues, extensions and substitutes thereof, the said entire interest to be held and enjoyed by ASSIGNEE for its own use and behoof and for the use and behoof of its successors and assigns to the full end of the term for which said Letters Patent may be granted in the United States, extensions and substitutes thereof, as fully and entirely as the same would have been held and enjoyed by ASSIGNOR had this sale not been made;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce said application, said invention and said Letters Patent which may be necessary or desirable to carry out the purposes hereof; and

ASSIGNOR HEREBY AUTHORIZES and requests the Commissioner of Patents and Trademarks to issue any and all Letters Patent, including any divisions, renewals, reissues and extension thereof to ASSIGNEE the aforesaid interest in and to the same.

ASSIGNOR FURTHER HEREBY AUTHORIZES the Attorney of Record in this application to fill in below the Serial number and filing date of this application subsequent to our execution of this assignment:

Serial No. _____ - Filing Date: _____

Name of Inventor	Residence	Post Office Address	Citizenship	Signature	Date
SHAO-YU TING	Hsinchu, TAIWAN	No. 9, Li Hsin Rd. Science-Based Industrial Park HSINCHU, TAIWAN	Taiwan, R.O.C.	 Shao-Yu Ting	5/11/01
JACK LIANG	Hsinchu, TAIWAN	No. 9, Li Hsin Rd. Science-Based Industrial Park HSINCHU, TAIWAN	Taiwan, R.O.C.		5/11/01
KUO-JU LIU	Hsinchu, TAIWAN	No. 9, Li Hsin Rd. Science-Based Industrial Park HSINCHU, TAIWAN	Taiwan, R.O.C.	Kuo-Ju Liu	5/11/01

PATENT

RECORDED: 01/07/2002

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